

ABSTRACT OF THE DISCLOSURE

A multi-chips stacked package at least comprises a substrate, an upper chip, a lower chip, a reinforced bump and a plurality of conductive bumps. The upper chip is flip-chip bonded to the upper surface of the substrate; and the lower chip is accommodated in the opening and flip-chip bonded to the upper chip. The reinforced bump is mounted onto the active surface of the upper chip and connected to the substrate so as to enhance the attachment of the upper chip to the substrate. In such a manner, the reinforced bump will restrain the thermal deformation of the substrate and the upper chip so as to prevent the electrically conductive bumps connecting the upper chip and the substrate from being damaged.